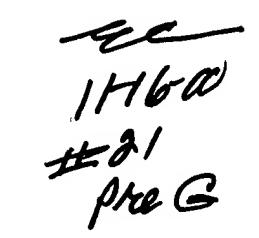
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Date of Deposit: November 8, 2000



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Our Case No. 7103/30-2

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PRELIMINARY AMENDMENT		
For	LINEAR POLISHER AND METHOD FOR SEMICONDUCTOR WAFER PLANARIZATION)))
Filing Date: May 8, 1997) Group Art Unit No. 3723
Serial No. 08/853,323) Examiner: G. Nguyen)
Homayoun Talieh et al.))
In re	Application of:)

Commissioner for Patents Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated May 8, 2000 please enter the following amendment and consider the following remarks:

IN THE CLAIMS:

Please amend claims 32, 34, 36-38, and 40 as follows:

(Five Times Amended) A polishing pad assembly for polishing a semiconductor wafer, said assembly comprising:

a belt forming a closed loop;

at least one non-[fixed]abrasive [chemical mechanical planarization] polishing pad mounted on the belt, the non-[fixed]abrasive [chemical mechanical planarization] polishing pad configured to receive a polishing slurry suitable for use in chemical mechanical planarization of the semiconductor wafer, wherein the non-[fixed]abrasive [chemical mechanical

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